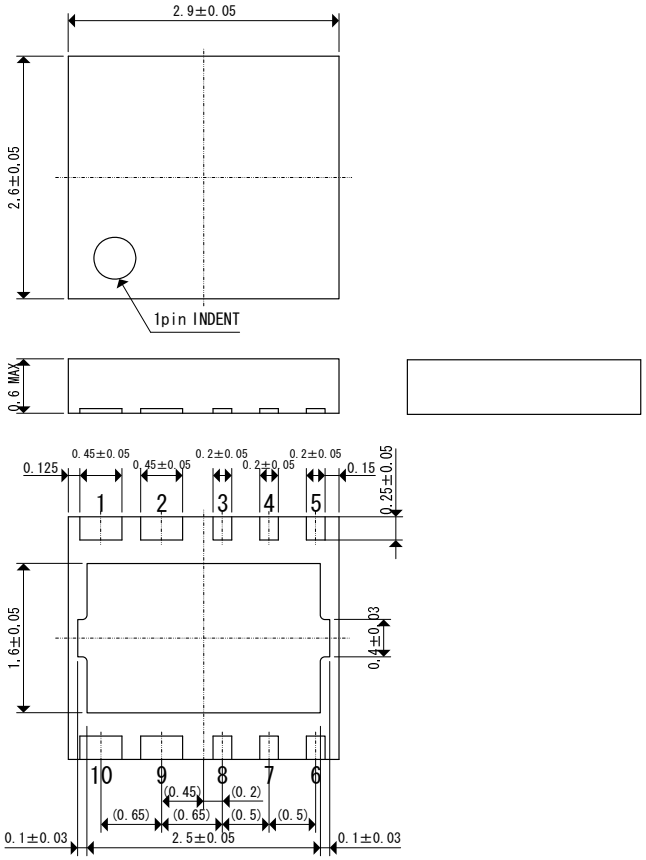
Packaging Information / Reference Pattern Layout Dimensions

●USP-10B

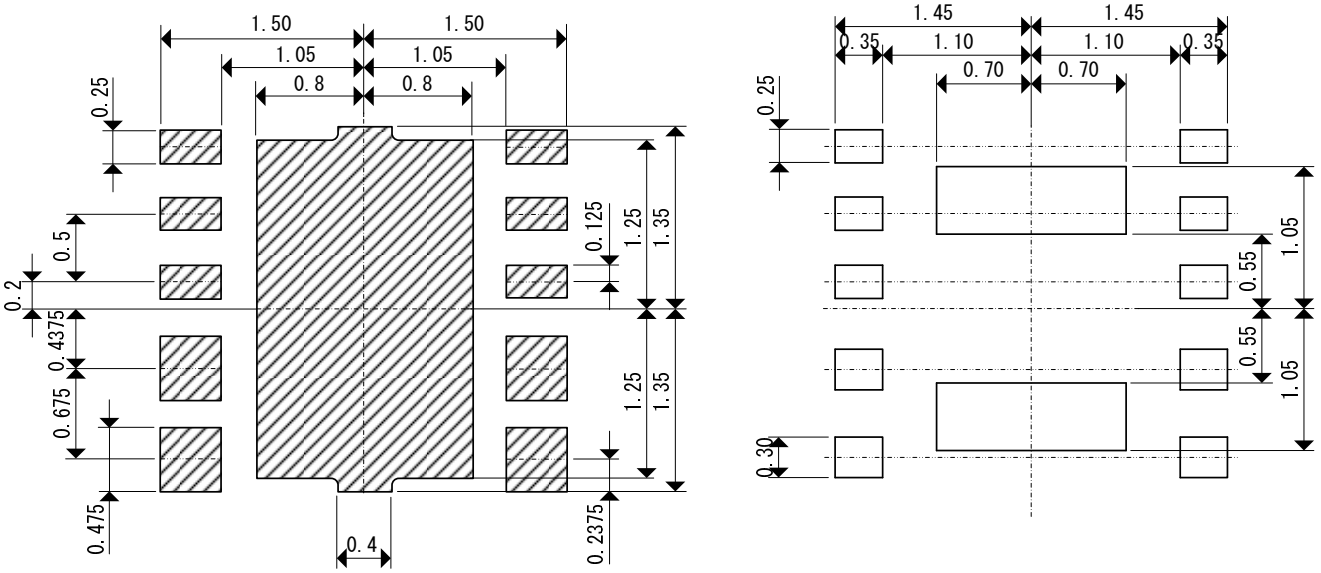
Unit: mm

■Packaging Information



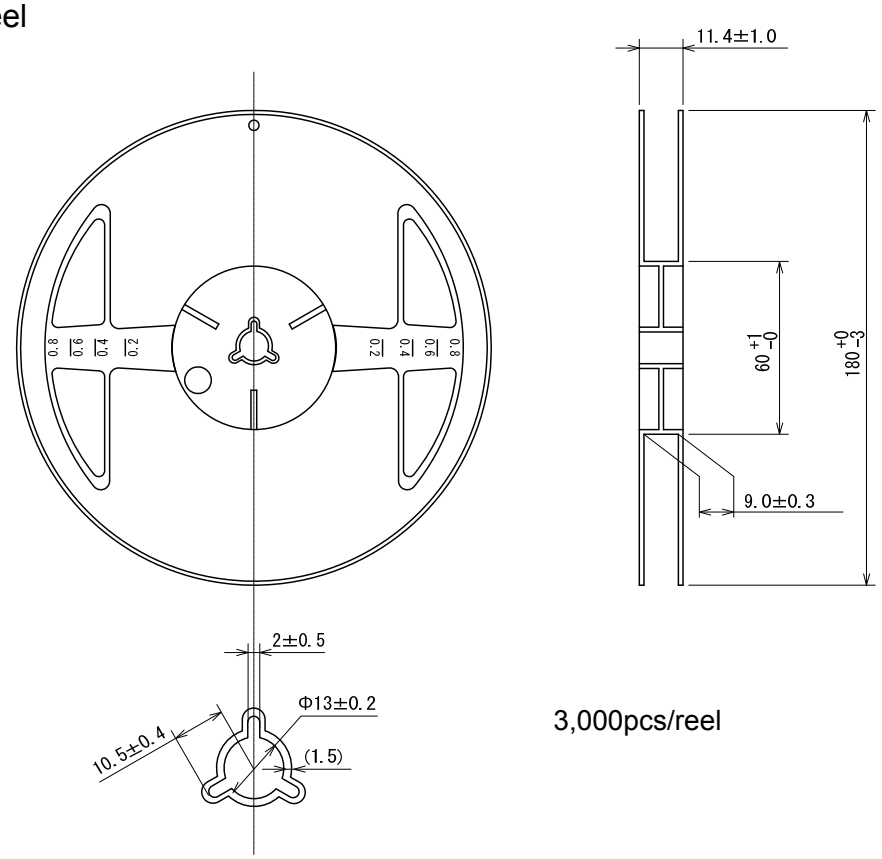
■Reference Pattern Layout Dimension

Note : reference metal mask design



Taping Specifications

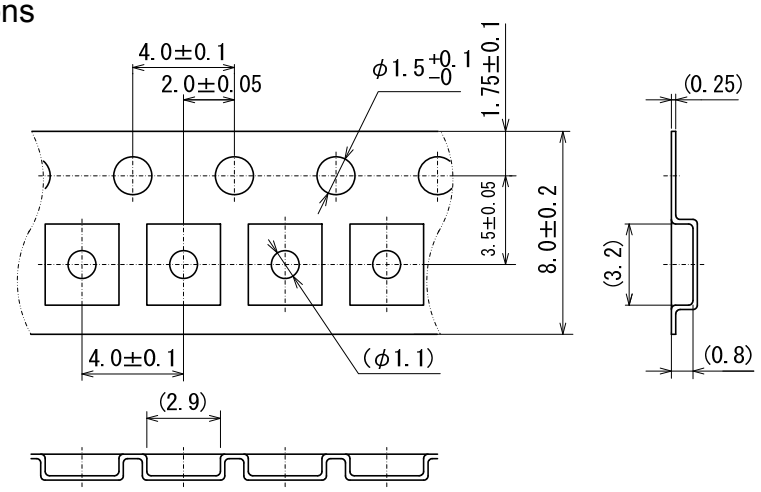
●USP-10B Reel



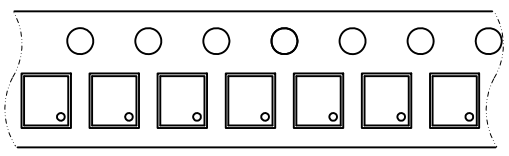
Unit: mm

3,000pcs/reel

●Taping Specifications



direction of feed



R Type :[Device orientation : Right]

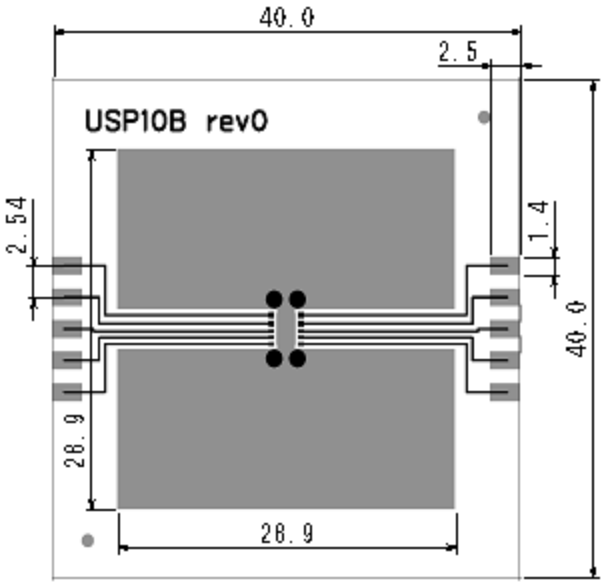
Standard feed

●USP-10B Power Dissipation

Power dissipation data for the USP-10B is shown in this page.
The value of power dissipation varies with the mount board conditions.
Please use this data as one of reference data taken in the described condition.

1. Measurement Condition (Reference data)

Condition : Mount on a board
Ambient : Natural convection
Soldering : Lead (Pb) free
Board : Dimensions 40mm×40mm（1600mm^2 in one side）
1st Inner Metal Layer about 50%
2nd Inner Metal Layer does not exist
3rd Inner Metal Layer does not exist
4th Inner Metal Layer about 50%
Each heat sink back metal is connected to the
Inner layers respectively.
Material : Glass Epoxy（FR-4）
Thickness : 1.6mm
Through-hole : 4 x 0.8 Diameter

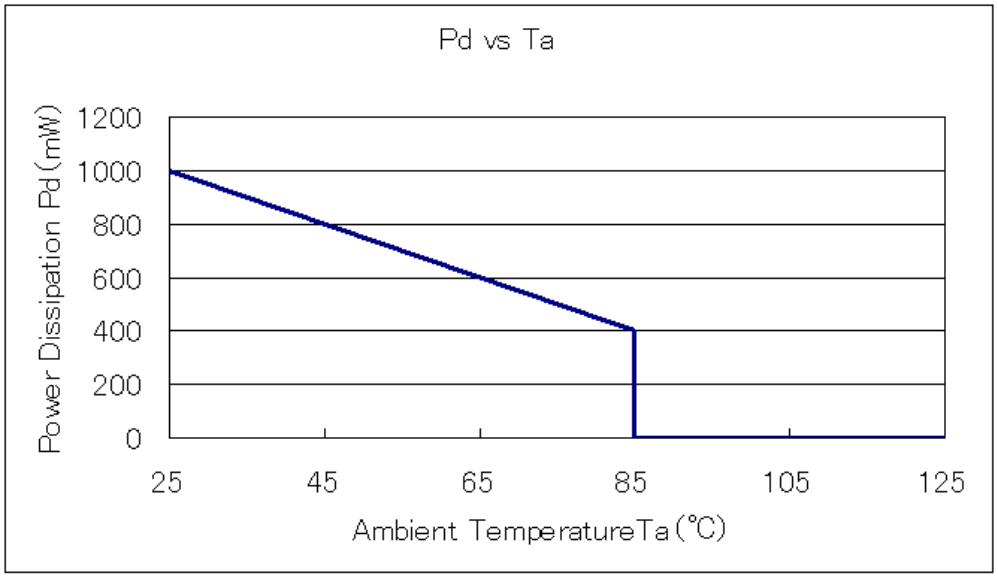


Evaluation Board (Unit: mm)

2. Power Dissipation vs. Ambient temperature

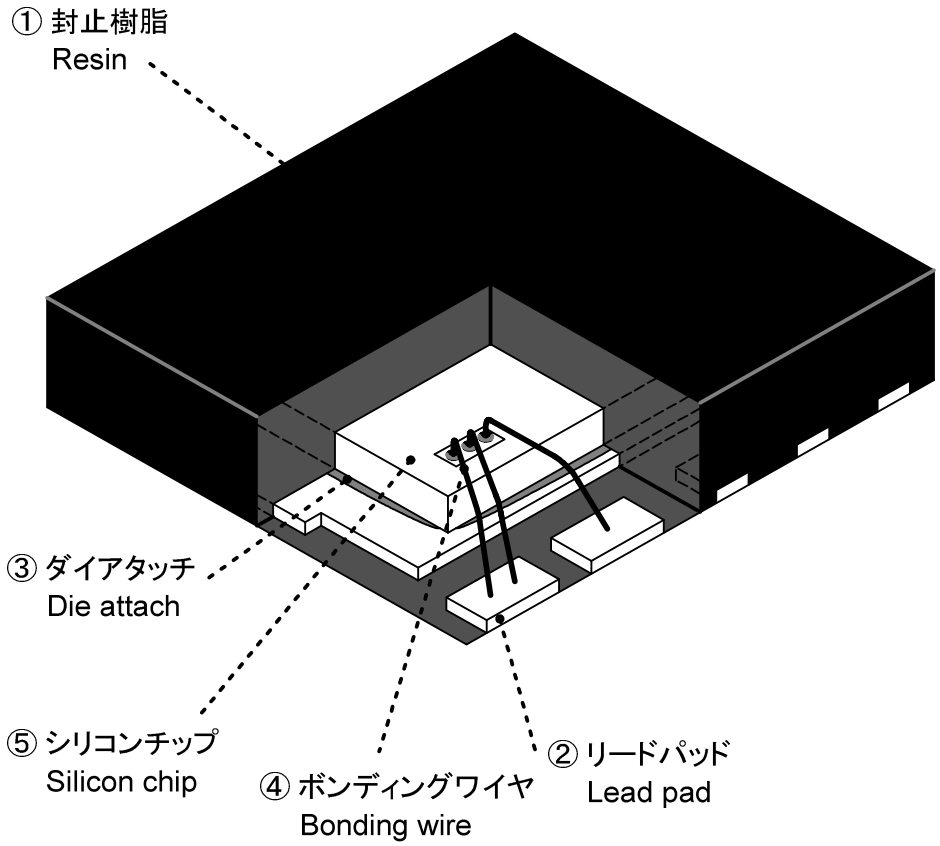
Board Mount (Tjmax=125℃)

Ambient Temperature (℃)	Power Dissipation Pd (mW)	Thermal Resistance (℃/W)
25	1000	100.00
85	400	



USP-10B 構造図
USP-10B Perspective

RoHS対応品
RoHS Compliance



項 目 Item		材 料 Material	備 考 Note
①	封止樹脂 Resin	エポキシ樹脂 Epoxy resin	難燃グレード/Flammability rating UL94V-0
②	リードパッド Lead pad	ニッケル Nickel	
	端子処理 Outer pad plating	Auメッキ Gold plating	端子側面は除く Except the side of the terminals.
③	ダイアタッチ Die attach	エポキシ Epoxy	
④	ボンディングワイヤ Bonding wire	Au	
⑤	シリコンチップ Silicon chip	Si	

捺印表示 Marking	レーザー Laser marking